Materials Declaration

Package	LFCSP
Body Size	4 X 4 x 0.85 mm
LeadCount	20
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	84.0	1.33 E-02	323499
Multiaromatic Resin	16.0	2.53 E-03	61613
Subtotal		1.58 E-02	385112

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	2.18 E-02	529492
Fe	2.35	5.24 E-04	12756
Zn	0.12	2.70 E-05	657
P	0.03	7.00 E-06	170
Subtotal		2.23 E-02	543076

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	4.36 E-04	10614

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.30 E-04	5599

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	4.17 E-04	10151

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.38 E-03	33594

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	70.0	3.40 E-04	8277
Resin	21.0	1.02 E-04	2483
Metal Oxide	3.0	1.50 E-05	365
Amine	3.0	1.50 E-05	365
Gamma Butyrolactone	3.0	1.50 E-05	365
Subtotal		4.87 E-04	11855

Package Totals

Weight (g)	PPM
4.11 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	None Detected	EPA Method 3051A/3052. ICP-OES
Cd	None Detected	EPA Method 3051A/3052. ICP-OES
Hg	None Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	None Detected	EPA3060A & 7196 A. UV-VIS
PBB	None Detected	EPA Method 3540C/3550C. GC/MS
PBDE	None Detected	EPA Method 3540C/3550C. GC/MS

Die Attach Paste

Item	PPM	Method
Pb	None Detected	EPA Method 3051A/3052. ICP-OES
Cd	None Detected	EPA Method 3051A/3052. ICP-OES
Hg	None Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	3	EPA3060A & 7196 A. UV-VIS
PBB	None Detected	EPA Method 3540C/3550C. GC/MS
PBDE	None Detected	EPA Method 3540C/3550C. GC/MS

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ADI Proprietary

Materials Declaration

Package	LFCSP
Body Size	4 X 4 x 0.85 mm
LeadCount	20
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	84.0	1.33 E-02	323349
Multiaromatic Resin	16.0	2.53 E-03	61585
Subtotal		1.58 E-02	384934

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	2.18 E-02	529247
Fe	2.35	5.24 E-04	12750
Zn	0.12	2.70 E-05	657
P	0.03	7.00 E-06	170
Subtotal		2.23 E-02	542824

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	4.36 E-04	10609

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85.0	2.12 E-04	5158
Pb	15.0	3.70 E-05	900
		2.49 E-04	6059

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	4.17 E-04	10146

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.38 E-03	33578

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	70.0	3.40 E-04	8273
Resin	21.0	1.02 E-04	2482
Metal Oxide	3.0	1.50 E-05	365
Amine	3.0	1.50 E-05	365
Gamma Butyrolactone	3.0	1.50 E-05	365
Subtotal		4.87 E-04	11850

Package Totals

Weight (g)	PPM
4.11 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	None Detected	EPA Method 3051A/3052. ICP-OES
Cd	None Detected	EPA Method 3051A/3052. ICP-OES
Hg	None Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	None Detected	EPA3060A & 7196 A. UV-VIS
PBB	None Detected	EPA Method 3540C/3550C. GC/MS
PBDE	None Detected	EPA Method 3540C/3550C. GC/MS

Die Attach Paste

Item	PPM	Method
Pb	None Detected	EPA Method 3051A/3052. ICP-OES
Cd	None Detected	EPA Method 3051A/3052. ICP-OES
Hg	None Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	3	EPA3060A & 7196 A. UV-VIS
PBB	None Detected	EPA Method 3540C/3550C. GC/MS
PBDE	None Detected	EPA Method 3540C/3550C. GC/MS

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